Description



The femtoSMDC series provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

Features

- RoHS compliant, lead-free and halogen free
- Fast response to fault currents
- Compact design saves board space
- Low resistance，Low-profile
- Compatible with high temperature solders

Applications

- USB peripherals，Disk drives，CD-ROMs
- Plug and play protection for motherboards and peripherals
- PDAs / digital cameras
- Game console port protection
- Tablet and Notebook PCs
- E-readers

Series Performance Specification

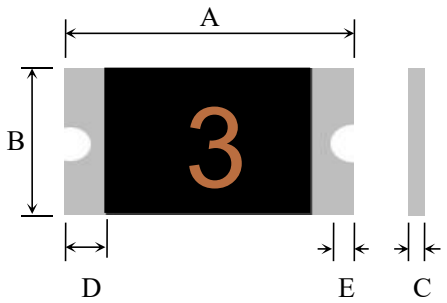
Model	Marking	V_{max} (Vdc)	I_{max} (A)	I_{hold} @25°C (A)	I_{trip} @25°C (A)	P_d Typ. (W)	Maximum Time To Trip		Resistance	
							Current (A)	Time (Sec)	$R_{i\ min}$ (Ω)	$R1_{max}$ (Ω)
SMD0805R035SF16V-1	3	16.0	30	0.35	0.75	0.5	8.0	0.10	0.200	1.200

Thermal Derading Chart

Recommended Hold Current(A) at Ambient Temperature(°C)

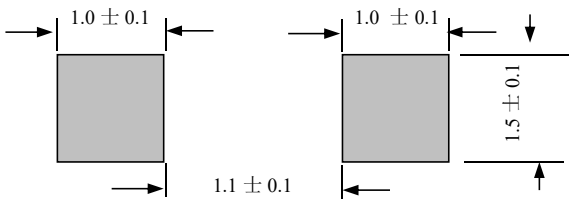
Model	Ambient Operation Temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD0805R035SF	0.47	0.44	0.39	0.35	0.30	0.27	0.24	0.20	0.14

Physical Dimensions(mm.)



	A		B		C		D	E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
SMD0805R035SF16V-1	2.00	2.20	1.20	1.50	0.35	0.80	0.20	0.10

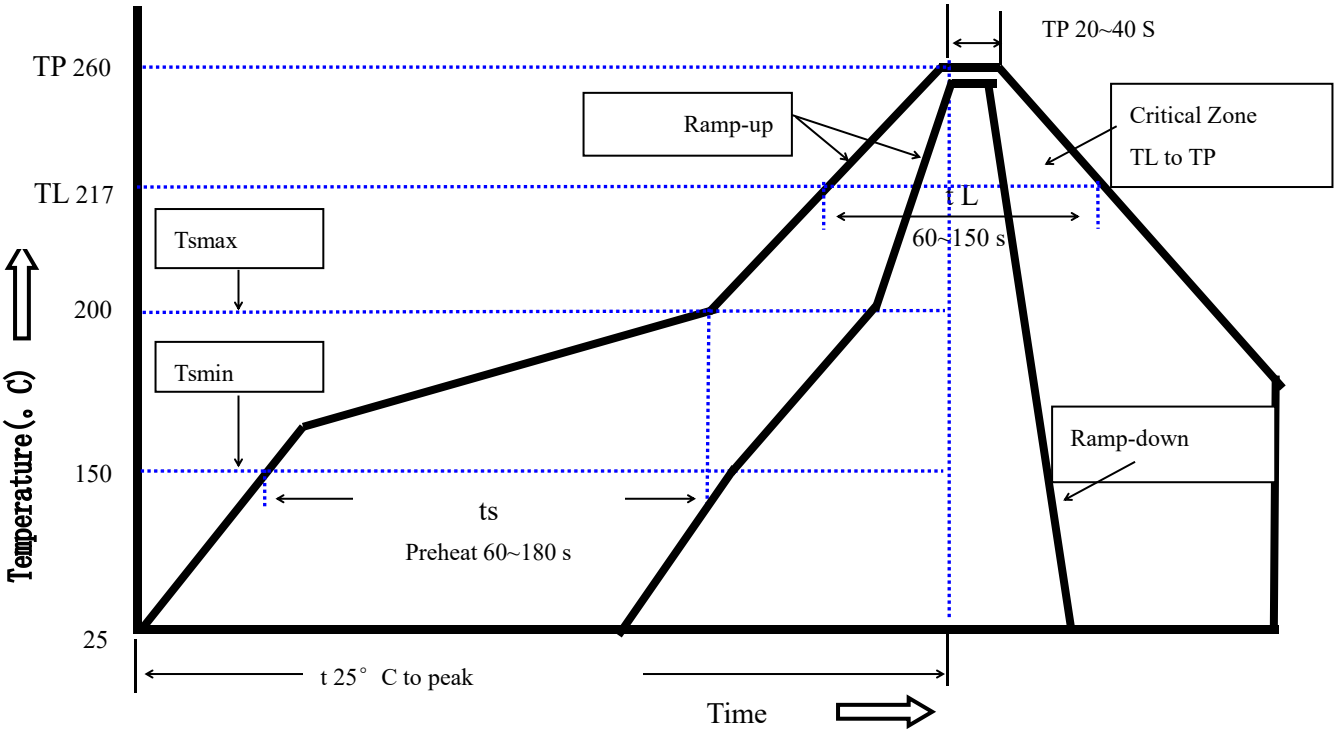
Recommended Pad Layout (mm.)



Packaging Quantity

Part Number	Quantity
SMD0805R035SF16V	5,000 pcs/reel

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(Ts max to T p)	3℃/second mac.
Preheat -Temperature Min(Ts min) -Temperature Max(Ts max) -Time(Ts min to Ts max)	 150℃ 200℃ 60~180 seconds
Time maintained above: -Temperature(TL) -Time(tL)	 217℃ 60~150 seconds
Peak Temperature(Tp)	260℃
Ramp-Down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max
Storage Condition	0℃~35℃,30%~60%RH

Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free

Recommended maximum paste thickness is 0.25mm

Devices can be cleaned using standard industry methods and solvents.

Note 1:All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.